505234642 12/13/2018

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1 Stylesheet Version v1.2 EPAS ID: PAT5281412

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
ROMEO WIECZOREK	10/08/2018

RECEIVING PARTY DATA

Name:	SMR PATENTS S.À.R.L.	
Street Address:	6, RUE EUGÈNE RUPPERT	
City:	LUXEMBOURG	
State/Country:	LUXEMBOURG	
Postal Code:	2453	

PROPERTY NUMBERS Total: 1

Property Type	Number
Application Number:	15458880

CORRESPONDENCE DATA

Fax Number: (212)755-7306

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent

using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 2123263939

Email: wtokmakidis@jonesday.com, gphillips@jonesday.com

Correspondent Name: JONES DAY

Address Line 1: 250 VESEY STREET

Address Line 4: NEW YORK, NEW YORK 10281

ATTORNEY DOCKET NUMBER:	13374-020-999
NAME OF SUBMITTER:	CRYSTAL ANN GOODSEIT
SIGNATURE:	/Crystal Ann Goodseit/
DATE SIGNED:	12/13/2018

Total Attachments: 2

source=13374-020-999 Assignment#page1.tif source=13374-020-999 Assignment#page2.tif

PATENT 505234642 REEL: 047764 FRAME: 0699

ASSIGNMENT

WHEREAS, I, Romeo WIECZOREK, citizen of Germany, having a mailing address of Waldackerweg 77/1, 73732 Esslingen, Germany, residing at Waldackerweg 77/1, 73732 Esslingen, Germany, ASSIGNOR, am the inventor of the invention in MODULAR ACTUATOR SYSTEM EMPLOYING SHAPE MEMORY ALLOY for which an application for a Patent of the United States has been filed.

- ☑ which was filed on 03/14/2018, Application No. 15/458,880

and WHEREAS, SMR Patents S.à.r.l., a corporation organized and existing under the laws of the state of Luxembourg, and having an office for the transaction of business at 6, Rue Eugène Ruppert, Luxembourg, LU 2453, ASSIGNEE, is desirous of obtaining my entire right, title and interest in, to and under the said invention and the said application:

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said ASSIGNEE, its successors, legal representatives and assigns, my entire right, title and interest in, to and under the said invention, and the said United States application and all divisions, renewals and continuations thereof, and all Patents of the United States which may be granted thereon and all reissues and extensions thereof; and all applications for industrial property protection, including, without limitation, all applications for patents, utility models, and designs which may be filed for said invention in any country or countries foreign to the United States, together with the right to file such applications and the right to claim for the same the priority rights derived from said United States application under the Patent Laws of the United States, the International Convention for the Protection of Industrial Property, or any other international agreement or the domestic laws of the country in which any such application is filed, as may be applicable; and all forms of industrial property protection, including, without limitation, patents, utility models, inventors' certificates and designs which may be granted for said invention in any country or countries foreign to the United States and all extensions, renewals and reissues thereof; and all right to sue for infringement including past infringement.

AND I HEREBY authorize and request the Commissioner for Patents and any Official of any country or countries foreign to the United States, whose duty it is to issue patents or other evidence or forms of industrial property protection on applications as aforesaid, to issue the same to the said ASSIGNEE, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND I HEREBY covenant and agree that I have full right to convey the entire interest herein assigned, and that I have not executed, and will not execute, any agreement in conflict herewith.

AND I HEREBY further covenant and agree that I will communicate to the said ASSIGNEE, its successors, legal representatives and assigns, any facts known to me respecting said invention, and testify in any legal proceeding, sign all lawful papers, execute all divisional, continuing, reissue and foreign applications, make all rightful oaths, and generally do everything possible to aid the said ASSIGNEE, its successors, legal representatives and assigns, to obtain and enforce proper protection for said invention in all countries.

U.S. Application No. 15/458,880 Fehler! Verweisquelle konnte nicht gefunden werden.					
	DDD TO DV AGGICNEE ON	AD Detents S à v.l.			
ACCEPTED AND AGR	EED TO BY ASSIGNEE, SM	MR Patents S.a.r.i.,:			
Date	, 2018				
		SMR Patents S.à.r.l.			
		Printed Name:			
		Title:			

Page 2 of 2